



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-09-24
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32MP257FAI3	E0AR*505XXXY	A	9991	2024-09-24
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	645	mg	Each	ECOPACK® 3

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Not Applicable	NAC	SACN305	
Package designator	Package size	Number of instances	Shape	
BGA	18x18	436	Bulk solder	
Comment	Package : B0MS FC TFBGA 18X18X1.2 436B P0.8 DM01034186			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E0AR*505XXX		644.8039		5000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	10.000	mg	supplier	die	Silicon(Si)	7440-21-3		9.329	mg	932860	14467.34327				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.005	mg	500	7.754295002				
				supplier	metallisation	Arsenic(As)	7440-38-2		0.000	mg	4	0.06203436				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.498	mg	49763	771.7539643				
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.000	mg	29	0.44974911				
				supplier	metallisation	Silver(Ag)	7440-22-4		0.002	mg	196	3.039683641				
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.005	mg	500	7.754295002				
				supplier	metallisation	Tin(Sn)	7440-31-5		0.107	mg	10667	165.4301296				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	108	1.67492772				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.006	mg	550	8.529724502				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.014	mg	1399	21.69651741				
				supplier	passivation	Silicon Oxide	7631-86-9		0.034	mg	3424	53.10141217				
				supplier	Solder Mask	Plastics PAK	Proprietary		5.238	mg	28290	8122.863017				
				Substrate (A32206)	Copper & Resin	185.142	mg	supplier	Solder Mask	Barium sulphate	7727-43-7		2.291	mg	11293	3242.541253
supplier	Solder Mask	Plastic EP	Proprietary						1.344	mg	7260	2084.552333				
supplier	Solder Mask	Silicon dioxide	7631-86-9						1.067	mg	5762	1654.433959				
supplier	Solder Mask	Additives, not to declare	Proprietary						0.480	mg	2593	744.5239945				
supplier	Solder Mask	Talc	14807-96-6						0.320	mg	1729	496.4450391				
supplier	Solder Mask	Pigment portion, not to declare	Proprietary						0.064	mg	346	99.34643351				
supplier	Solder Mask	Inorganic Ingredient, not to declare	Proprietary						0.064	mg	346	99.34643351				
supplier	PP	Thermosetting resin (including filler)	Proprietary						33.242	mg	179550	51553.90791				
supplier	PP	Glass Cloth	65997-17-3						22.161	mg	119700	34369.27194				
supplier	Cu foil	Copper	7440-50-8						13.390	mg	72325	20766.56302				
supplier	Cu Plating	Copper	7440-50-8						105.680	mg	570806	163894.6252				
Underfill (UA26)	Encapsulation Glue	2.000	mg					supplier	Underfill	p-(2,3-epoxypropoxy)-N, N-bis(2,3-epoxypropyl)a	5026-74-4		0.200	mg	100000	310.1718001
								supplier	Underfill	Bisphenol F type liquid epoxy resin	9003-36-5		0.200	mg	100000	310.1718001
								supplier	Underfill	Bisphenol A type liquid epoxy resin	25068-38-6		0.060	mg	30000	93.05154002
				supplier	Underfill	Amine type hardener	Proprietary		0.140	mg	70000	217.12026				
				supplier	Underfill	Carbon black	1333-86-4		0.010	mg	5000	15.50859				
				supplier	Underfill	Silicon dioxide	60676-86-0		1.300	mg	650000	2016.1167				
				supplier	Underfill	Additives	Proprietary		0.090	mg	45000	139.57731				
Encapsulation (EME-G760-SW)	Molding Compound	339.599	mg	supplier	Molding compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-di	85954-11-6		16.980	mg	50000	26333.53697				
				supplier	Molding compound	Phenol Resin A	9003-35-4		13.584	mg	40000	21066.82958				
				supplier	Molding compound	Phenol Resin B	Proprietary		13.584	mg	40000	21066.82958				
				supplier	Molding compound	Silica(Amorphous) A	60676-86-0		212.250	mg	625000	329169.2122				
				supplier	Molding compound	Silica(Amorphous) B	7631-86-9		67.920	mg	200000	105334.1479				
				supplier	Molding compound	Metal Hydroxide	Proprietary		13.584	mg	40000	21066.82958				
				supplier	Molding compound	Carbon Black	1333-86-4		1.698	mg	5000	2633.353697				
Solder balls (SACN305)	Other inorganic materials	108.063	mg	supplier	Solder Ball	Tin	7440-31-5		104.335	mg	965500	161808.6586				
				supplier	Solder Ball	Silver	7440-22-4		3.134	mg	29000	4860.125428				
				supplier	Solder Ball	Copper	7440-50-8		0.540	mg	5000	837.9526599				
				supplier	Solder Ball	Nickel	7440-02-0		0.054	mg	500	83.79526599				